



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

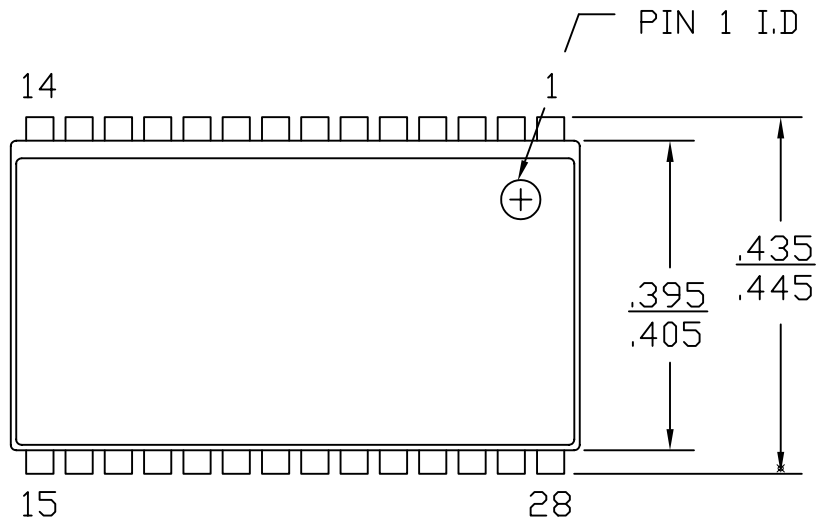
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

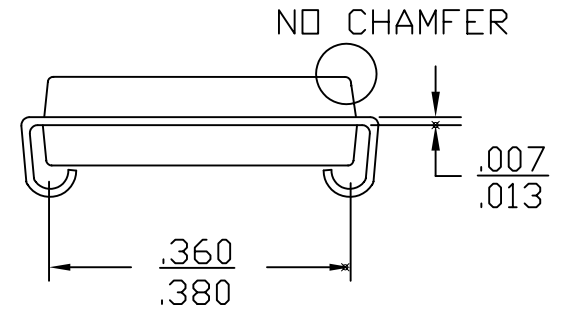
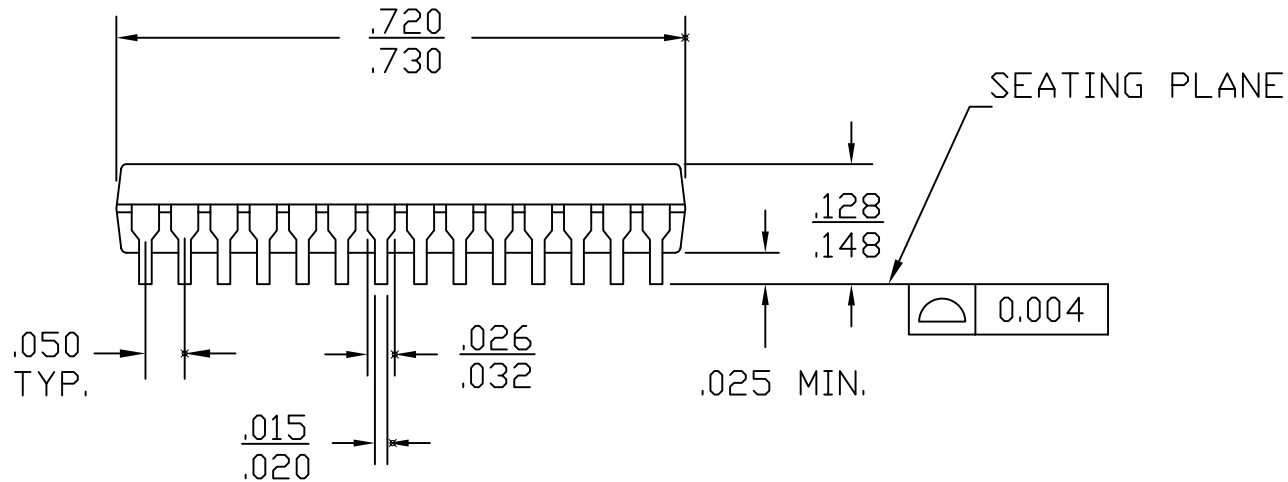
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

28 Lead (400 MIL) Molded SOJ V28



DIMENSIONS IN INCHES MIN.
MAX.




NOTES :

1. PACKAGE WEIGHT : 1.24g
2. JEDEC REFERENCE : MS-027

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

PACKAGE CODE(S) V28.4

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 28L SOJ 400 MILS V28.4 (MOLDED SOJ V28)	
SPEC NO. 51-85032	REV *F
SCALED TO FIT	N/A
SHEET 1 OF 2	

Rev.	ECN No.	Origin of Change	Description of Change
**	N/A		N/A
*A	49389		CHG. TITLE
*B	60088		REMOVE DETAIL "A"
*C	2871406		Changed template, & title from 28LD (400 MIL) SOJ PKG OULINE to
*D	2887115		Removed chamfer on pin #1 corner
*E	3146953		ECN SUNSET NO CHANGE
*F	4257179	KTQAD/ XANC	SUNSET REVIEW. CHANGED DRAWING TEMPLATE.



CYPRESS
Company Confidential

TITLE
PACKAGE OUTLINE, 28L SOJ 400 MILS V28.4
(MOLDED SOJ V28)

SPEC NO. 51-85032	REV *F
SCALED TO FIT	N/A
SHEET 2 OF 2	

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

PACKAGE
CODE(S)

V28.4